SN75159
<b>DUAL DIFFERENTIAL LINE DRIVER</b>
WITH 3-STATE OUTPUTS
SLLS088B – JANUARY 1977 – REVISED MAY 1995

14 🛛 V<sub>CC</sub>

12 2Y

П 2В

72A

2EN

13 🛛 2Z

11

10

9

8

NC-No internal connection

D OR N PACKAGE (TOP VIEW)

NC

1Z[] 2

1AΠ

1B[] 5

1EN 6

GND [

1Y[] 3

4

7

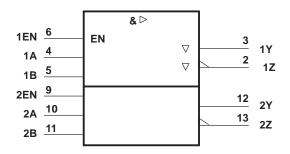
- Meets or Exceeds the Requirements of ANSI EIA/TIA-422-B and ITU Recommendation V.11
- Single 5-V Supply
- Balanced Line Operation
- TTL Compatible
- High-Impedance Output State for Party-Line Applications
- High-Current Active-Pullup Outputs
- Short-Circuit Protection
- Dual Channels
- Clamp Diodes at Inputs

# description

The SN75159 dual differential line driver with 3-state outputs is designed to provide all the features of the SN75158 line driver with the added feature of driver output controls. There is an individual control for each driver. When the output control is low, the associated outputs are in a high-impedance state and the outputs can neither drive nor load the bus. This permits many devices to be connected together on the same transmission line for party-line applications.

The SN75159 is characterized for operation from 0°C to 70°C.

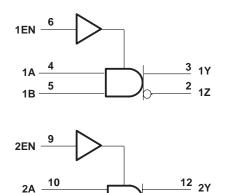
### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)

2B 11





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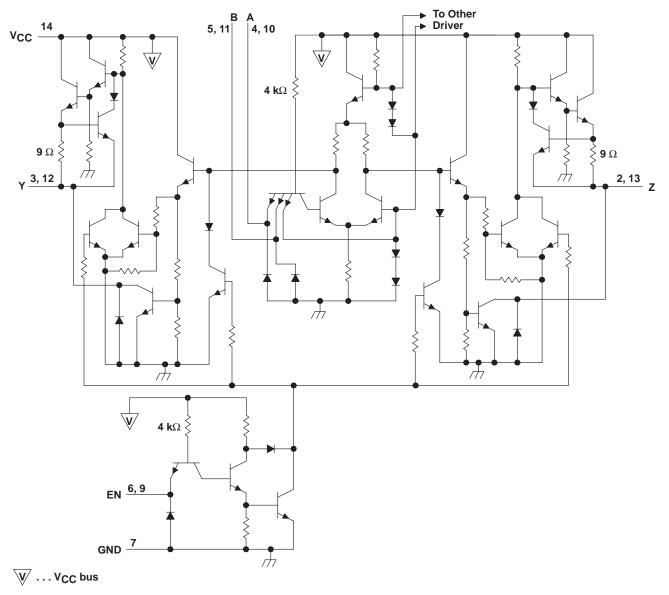


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<sup>13</sup> 2Z

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## schematic (each driver)



Resistor values shown are nominal.



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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage, V <sub>1</sub>	5.5 V
Off-state voltage applied to open-collector outputs	12 V
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values except differential output voltage VOD are with respect to the network ground terminal. VOD is at the Y output with respect to the Z output.

DISSIPATION RATING TABLE									
PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING						
D	950 mW	7.6 mW/°C	608 mW						
Ν	1150 mW	9.2 mW/°C	736 mW						

#### recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.75	5	5.25	V
High-level input voltage, VIH	2			V
Low-level input voltage, VIL			0.8	V
High-level output voltage, I <sub>OH</sub>			-40	mA
Low-level output current, I <sub>OL</sub>			40	mA
Operating free-air temperature, T <sub>A</sub>	0		70	°C



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#### electrical characteristics over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	MIN	TYP†	MAX	UNI		
VIK	Input clamp voltage	V <sub>CC</sub> = 4.75 V,			-0.9	-1.5	V	
Vон	High-level output voltage	V <sub>CC</sub> = 4.75 V, V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -40 mA	2.4	3		V	
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = 4.75 V, V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 40 mA			0.25	0.4	V
Vок	Output clamp voltage	V <sub>CC</sub> = 5.25 V,	$I_{O} = -40 \text{ mA}$			-1.1	-1.5	V
VO	Output voltage	V <sub>CC</sub> = 4.75 V to 5.25 V,	IO = 0		0		6	V
IVOD1	Differential output voltage	V <sub>CC</sub> = 5.25 V,	I <mark>O</mark> = 0			3.5	2V <sub>OD2</sub>	V
IVOD2	Differential output voltage	V <sub>CC</sub> = 4.75 V			2	3		V
	Change in magnitude of differential output voltage‡	V <sub>CC</sub> = 4.75 V			±0.02	±0.4	V	
Vee	Common-mode output	V <sub>CC</sub> = 5.25 V	D. 100.0			1.8	3	v
VOC	voltage§	V <sub>CC</sub> = 4.75 V	R <sub>L</sub> = 100 Ω,	See Figure 1		1.5	3	V
∆ VOC	Change in magnitude of common-mode output voltage‡	V <sub>CC</sub> = 4.75 V to 5.25 V			±0.01	±0.4	V	
			V <sub>O</sub> = 6 V			0.1	100	
IO	Output current with power off	$V_{CC} = 0$	$V_{O} = -0.25 V$			-0.1	-100	μA
			$V_{O} = -0.25 V$	to 6 V			±100	
			$T_A = 25^{\circ}C$	$V_{O} = 0$ to $V_{CC}$			±10	
				$V_{O} = 0$			-20	
IOZ	Off-state (high-impedance state) output current	$V_{CC} = 5.25 V$ , Output controls at 0.8 V	T <sub>A</sub> = 70°C	V <sub>O</sub> = 0.4 V			±20	μΑ
			1A = 70 0	V <sub>O</sub> = 2.4 V			±20	
				$V_{O} = V_{CC}$			20	
łı	Input current at maximum input voltage	V <sub>CC</sub> = 5.25 V,	V <sub>I</sub> = 5.5 V				1	mA
Ι <sub>ΙΗ</sub>	High-level input current	V <sub>CC</sub> = 5.25 V,	VI = 2.4 V				40	μA
۱ <sub>IL</sub>	Low-level input current	V <sub>CC</sub> = 5.25 V,	V <sub>I</sub> = 0.4 V			-1	-1.6	mA
los	Short-circuit output current¶	V <sub>CC</sub> = 5.25 V			-40	-90	-150	mA
ICC	Supply current (both drivers)	V <sub>CC</sub> = 5.25 V, T <sub>A</sub> = 25°C,	Inputs ground No load	ed,		47	65	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5$  V and  $T_A = 25^{\circ}C$  except for  $V_{OC}$ , for which  $V_{CC}$  is as stated under test conditions.

<sup>‡</sup> Δ|V<sub>OD</sub>| and Δ|V<sub>OC</sub>| are the changes in magnitudes of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input is changed from a high level to a low level.

\$ In ANSI Standard EIA/TIA-422-B, V<sub>OC</sub>, which is the average of the two output voltages with respect to GND, is called output offset voltage, V<sub>OS</sub>.  $\P$  Only one output should be shorted at a time, and duration of the short circuit should not exceed one second.



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# switching characteristics over operating free-air temperature range, $V_{CC}$ = 5 V

	PARAMETER	TEST CONDITION	S	MIN	түр†	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output	$C_1 = 30 \text{ pF}, R_1 = 100 \Omega, \text{ See Figure 2}$			16	25	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	Termination A			11	20	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output	C <sub>I</sub> = 15 pF, See Figure 2, Te			13	20	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	$C_{L} = 15  \text{pr},  \text{See Figure 2},  \text{Rec}$			9	15	ns
ttlh	Transition time, low-to-high-level output	$C_{L} = 30 \text{ pF}, R_{L} = 100 \Omega, S_{L}$	ee Figure 2,		4	20	ns
<sup>t</sup> THL	Transition time, high-to-low-level output	Termination A			4	20	ns
<sup>t</sup> PZH	Output enable time to high level	$C_L = 30 \text{ pF}, R_L = 180 \Omega, S_L$	ee Figure 3		7	20	ns
t <sub>PZL</sub>	Output enable time to low level	$C_L = 30 \text{ pF}, R_L = 250 \Omega, S_{C_L}$	ee Figure 4		14	40	ns
<sup>t</sup> PHZ	Output disable time from high level	$C_{L} = 30 \text{ pF}, R_{L} = 180 \Omega, S_{L}$	ee Figure 3		10	30	ns
<sup>t</sup> PLZ	Output disable time from low level	$C_{L} = 30 \text{ pF}, R_{L} = 250 \Omega, S_{L}$	ee Figure 4		17	35	ns
	Overshoot factor	$R_L = 100 \Omega$ , See Figure 2, Te	ermination C			10%	

<sup>†</sup> All typical values are at  $T_A = 25^{\circ}C$ .

DATA-SHEET PARAMETER	EIA/TIA-422-B
VO	V <sub>oa,</sub> V <sub>ob</sub>
VOD1	Vo
IVOD2	Vt
$\Delta  V_{OD} $	$  V_t  -  \overline{V}_t  $
V <sub>OC</sub>	V <sub>OS</sub>
$\Delta  V_{OC} $	$ V_{OS} - \overline{V}_{OS} $
los	<sub>sa</sub>   ,    <sub>sb</sub>
IO	I <sub>xa</sub>   ,  I <sub>xb</sub>

#### SYMBOL EQUIVALENTS

#### PARAMETER MEASUREMENT INFORMATION

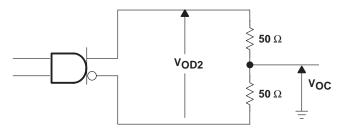
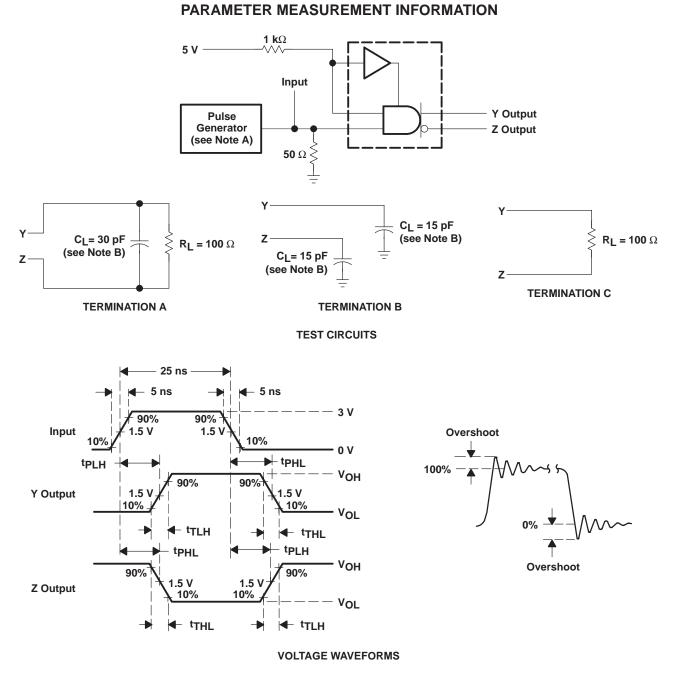


Figure 1. Differential and Common-Mode Output Voltages



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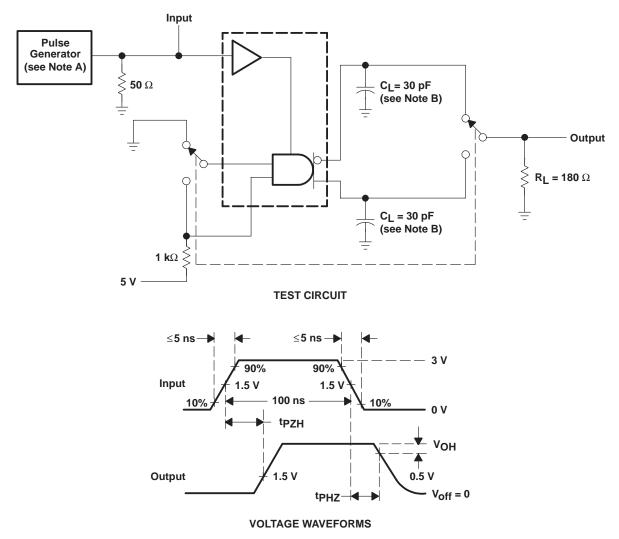


NOTES: A. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , PRR  $\leq 10$  MHz. B. C<sub>L</sub> includes probe and jig capacitance.

Figure 2. Test Circuits, Voltage Waveforms, and Overshoot Factor



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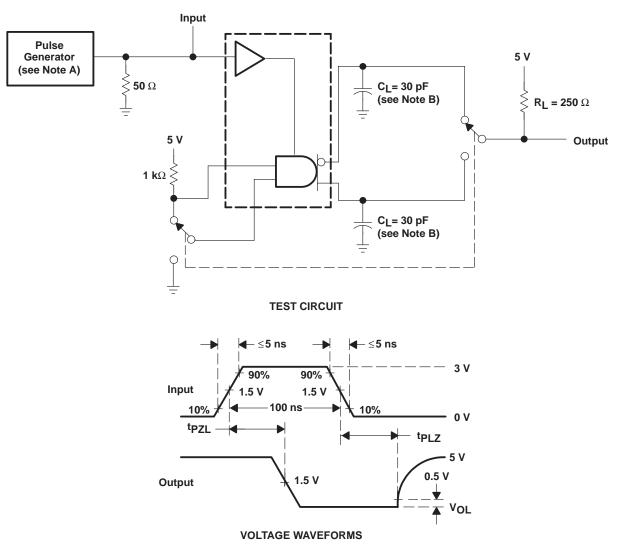
#### PARAMETER MEASUREMENT INFORMATION

NOTES: A. The pulse generator has the following characteristics:  $Z_0 = 50 \Omega$ , PRR  $\leq 500 \text{ kHz}$ . B. CL includes probe and jig capacitance.

Figure 3. Test Circuit and Voltage Waveforms



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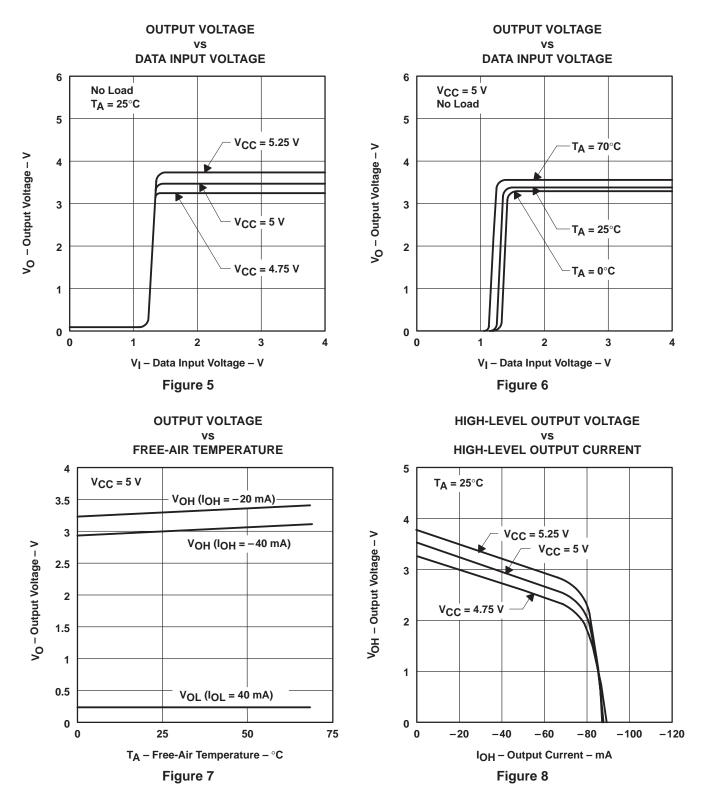
PARAMETER MEASUREMENT INFORMATION

NOTES: A. The pulse generator has the following characteristics:  $Z_0 = 50 \Omega$ , PRR  $\leq 500 \text{ kHz}$ . B. CL includes probe and jig capacitance.

Figure 4. Test Circuit and Voltage Waveform

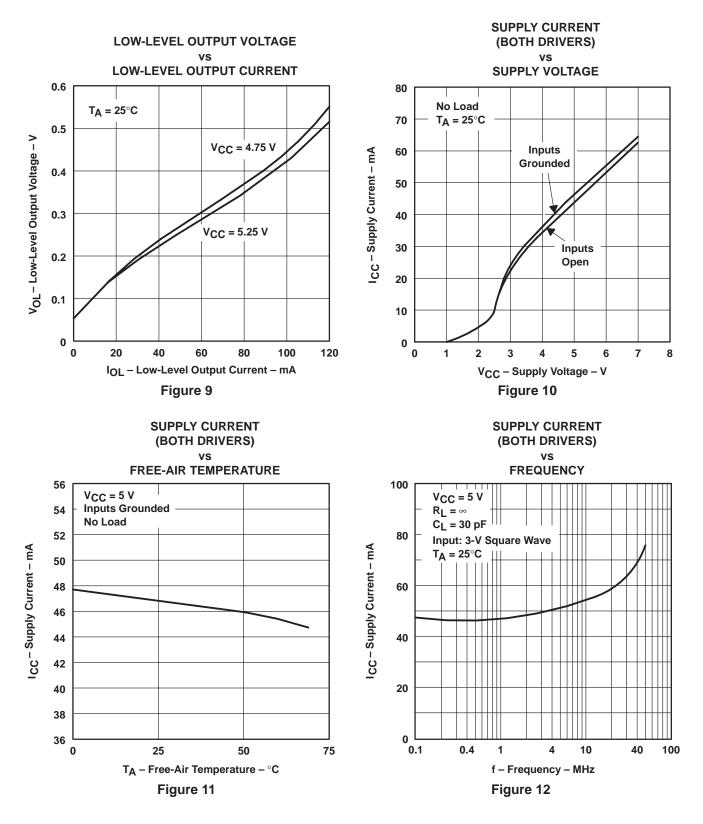


#### **TYPICAL CHARACTERISTICS**





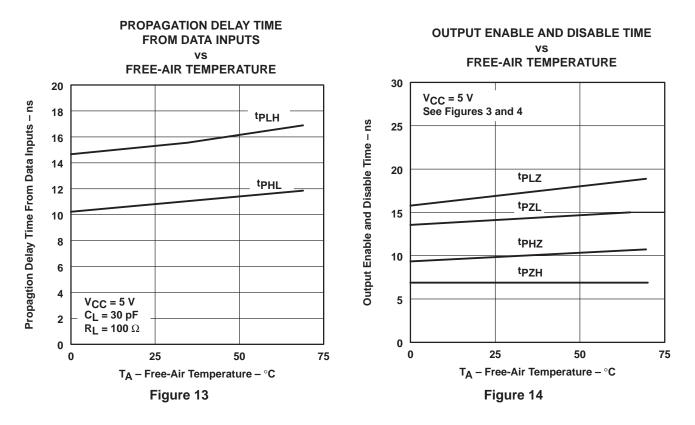






#### SN75159 DUAL DIFFERENTIAL LINE DRIVER WITH 3-STATE OUTPUTS SLLS088B – JANUARY 1977 – REVISED MAY 1995

#### **TYPICAL CHARACTERISTICS**







### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75159D	LIFEBUY	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75159	
SN75159N	LIFEBUY	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75159N	

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## TUBE



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN75159D	D	SOIC	14	50	506.6	8	3940	4.32
SN75159N	N	PDIP	14	25	506	13.97	11230	4.32

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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